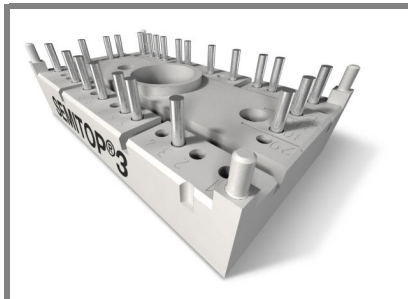


# SK 150 MHK 055 T



SEMITOP® 3

## Mosfet Module

SK 150 MHK 055 T

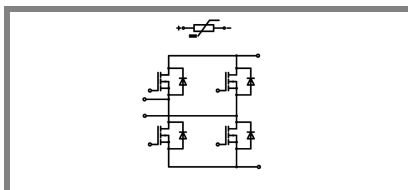
Target Data

### Features

- Compact design
- One screw mounting
- Heat transfer and isolation through direct copper bonded aluminium oxide ceramic (DCB)
- Trench technology
- Short internal connections and low inductance case
- Integrated PTC temperature sensor

### Typical Applications\*

- Low switched mode power supplies
- DC servo drives
- UPS



MHK

Absolute Maximum Ratings		$T_s = 25\text{ }^\circ\text{C}$ , unless otherwise specified	
Symbol	Conditions	Values	Units
<b>MOSFET</b>			
$V_{DSS}$		55	V
$V_{GSS}$		$\pm 20$	V
$I_D$	$T_s = 25\text{ (80) }^\circ\text{C}$ ;	240 (150)	A
$I_{DM}$	$t_p < 1\text{ ms}$ ; $T_s = 25\text{ (80) }^\circ\text{C}$ ;	340 (250)	A
$T_j$		-40...+150	$^\circ\text{C}$
<b>Inverse diode</b>			
$I_F = -I_D$	$T_s = 25\text{ (80) }^\circ\text{C}$ ;	240 (150)	A
$I_{FM} = -I_{DM}$	$t_p < 1\text{ ms}$ ; $T_s = 25\text{ (80) }^\circ\text{C}$ ;	340 (250)	A
$T_j$		-40...+150	$^\circ\text{C}$
<b>Freewheeling CAL diode</b>			
$I_F = -I_D$	$T_s = \text{ }^\circ\text{C}$		A
$T_j$			$^\circ\text{C}$
$T_{stg}$		-40 ... +125	$^\circ\text{C}$
$T_{sol}$	Terminals, 10 s	260	$^\circ\text{C}$
$V_{isol}$	AC, 1 min (1s)	2500 / 3000	V

Characteristics		$T_s = 25\text{ }^\circ\text{C}$ , unless otherwise specified			
Symbol	Conditions	min.	typ.	max.	Units
<b>MOSFET</b>					
$V_{(BR)DSS}$	$V_{GS} = 0\text{ V}$ ; $I_D = 0,25\text{ mA}$	55			V
$V_{GS(th)}$	$V_{GS} = V_{DS}$ ; $I_D = 0,25\text{ mA}$	2,5	3,2	4,5	V
$I_{DSS}$	$V_{GS} = 0\text{ V}$ ; $V_{DS} = V_{DSS}$ ; $T_j = 25\text{ (125) }^\circ\text{C}$			1	$\mu\text{A}$
$I_{GSS}$	$V_{GS} = \pm 20\text{ V}$ ; $V_{DS} = 0\text{ V}$			100	nA
$R_{DS(on)}$	$I_D = 5\text{ A}$ ; $V_{GS} = 10\text{ V}$ ; $T_j = 25\text{ }^\circ\text{C}$		1,1	1,5	m $\Omega$
$R_{DS(on)}$	$I_D = 5\text{ A}$ ; $V_{GS} = 10\text{ V}$ ; $T_j = 125\text{ }^\circ\text{C}$		1,9	2,6	m $\Omega$
$C_{CHC}$	per MOSFET				pF
$C_{iss}$	under following conditions:		21,2		nF
$C_{oss}$	$V_{GS} = 0\text{ V}$ ; $V_{DS} = 25\text{ V}$ ; $f = 1\text{ MHz}$		3,3		nF
$C_{rss}$			1,6		nF
$L_{DS}$					nH
$t_{d(on)}$	under following conditions:		40		ns
$t_r$	$V_{DD} = 30\text{ V}$ ; $V_{GS} = 10\text{ V}$ ; $I_D = 70\text{ A}$		180		ns
$t_{d(off)}$	$R_G = 2,5\text{ }\Omega$		70		ns
$t_f$			110		ns
$R_{th(j-s)}$	per MOSFET (per module)			0,8	K/W
<b>Inverse diode</b>					
$V_{SD}$	$I_F = 5\text{ A}$ ; $V_{GS} = 0\text{ V}$ ; $T_j = 25\text{ }^\circ\text{C}$		0,7	1,5	V
$I_{RRM}$	under following conditions:		8		A
$Q_{rr}$	$I_F = 150\text{ A}$ ; $T_{vj} = 25\text{ }^\circ\text{C}$ ; $R_G = 2,5\text{ }\Omega$		0,35		$\mu\text{C}$
$t_{rr}$	$V_R = 30\text{ A}$ ; $di/dt = 100\text{ A}/\mu\text{s}$		80		ns
<b>Free-wheeling diode</b>					
$V_F$	$I_F = \text{A}$ ; $V_{GS} = \text{V}$				V
$I_{RRM}$	under following conditions:				A
$Q_{rr}$	$I_F = \text{A}$ ; $T_{vj} = \text{ }^\circ\text{C}$				$\mu\text{C}$
$t_{rr}$	$V_r = \text{A}$ ; $di/dt = \text{A}/\mu\text{s}$				ns
<b>Mechanical data</b>					
M1	mounting torque			2,5	Nm
w			30		g
Case	SEMITOP® 3		T 64		

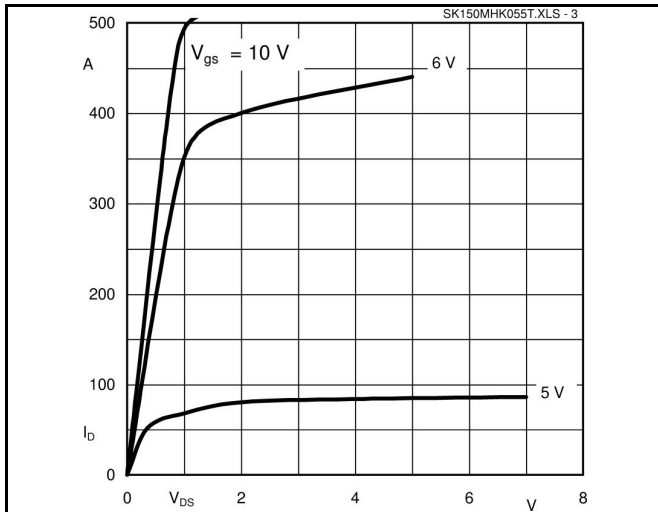


Fig. 3 Output characteristic,  $t_p = 80 \mu s$ ,  $T_J = 25^\circ C$

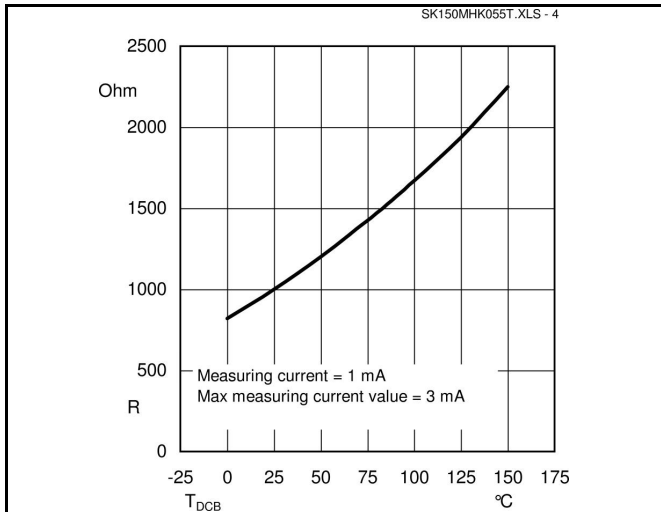


Fig. 4 Typ. PTC Characteristic

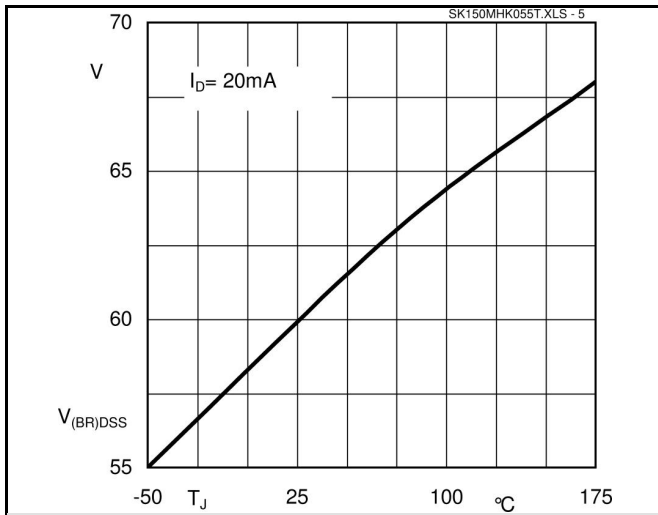


Fig. 5 Breakdown voltage vs. temperature

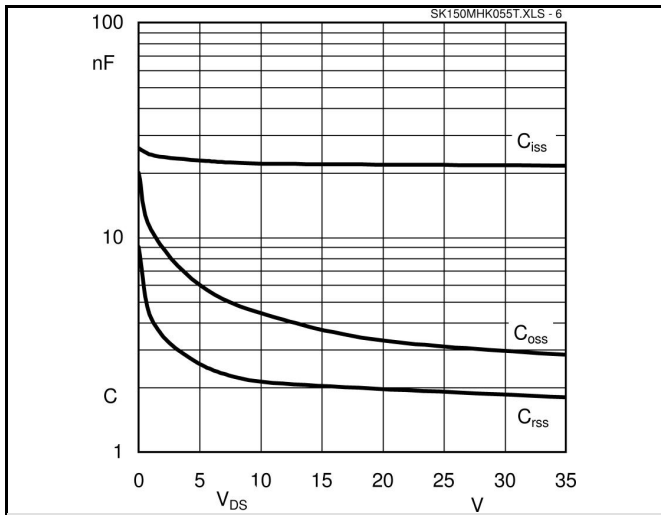


Fig. 6 Typ. capacitances vs. drain-source voltage

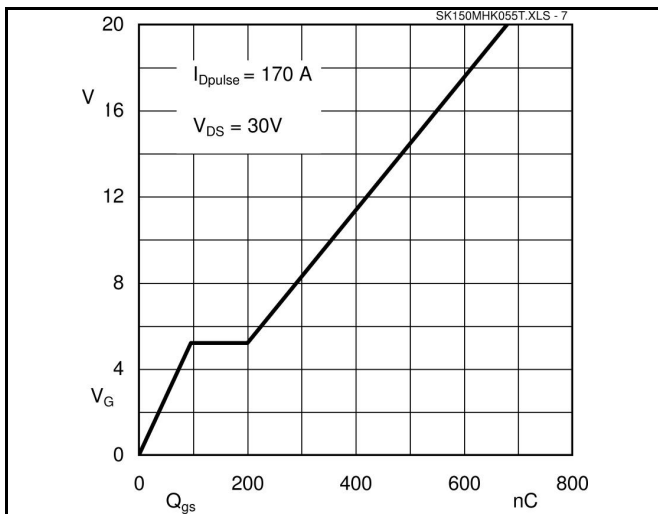


Fig. 7 Gate charge characteristic

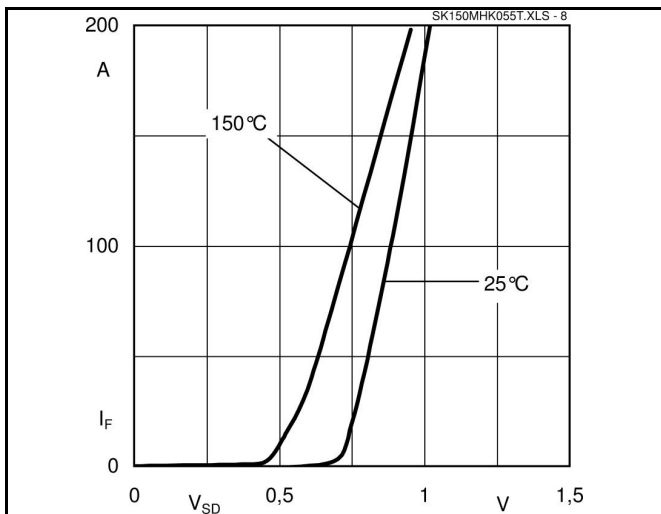
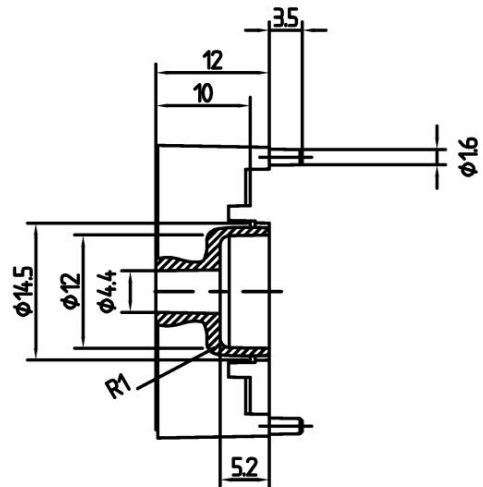
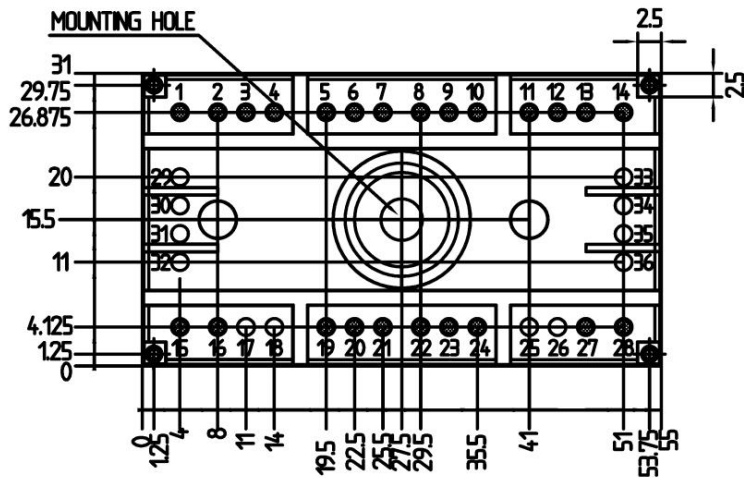
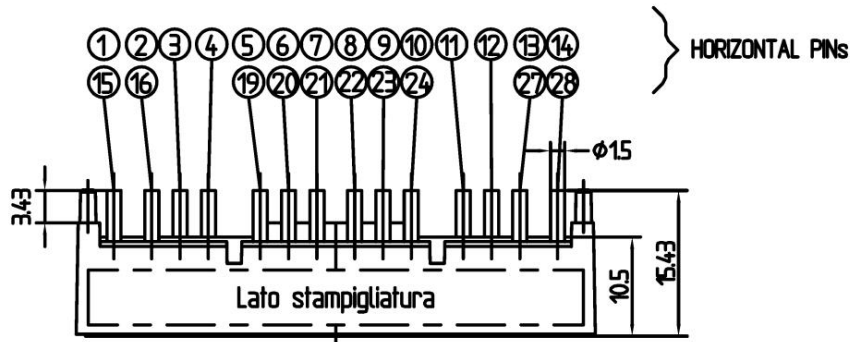


Fig. 8 Diode forward characteristic,  $t_p = 80 \mu s$

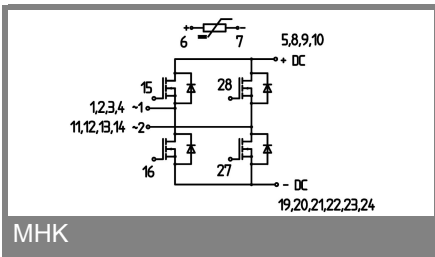
# SK 150 MHK 055 T

Dimensions in mm



SUGGESTED HOLEDIAMETER FOR THE SOLDER PINS AND THE MOUNTING PINS IN THE PCB: 2 mm

Case T64



MHK

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

\* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our personal.